OBSOLETE

MICRON TECHNOLOGY, INC.

1, 2, 4 MEG x 32
DRAM SODIMMs

SMALL-OUTLINE DRAM MODULE

MT2LDT132H(X)(S), MT4LDT232H(X)(S), MT8LDT432H(X)(S)

For the latest data sheet revisions, please refer to the Micron Web site: www.micron.com/mti/msp/html/datasheet.html

FEATURES

- JEDEC pinout in a 72-pin, small-outline, dual in-line memory module (DIMM)
- 4MB (1 Meg x 32), 8MB (2 Meg x 32) and 16MB (4 Meg x 32)
- High-performance CMOS silicon-gate process
- Single +3.3V ±0.3V power supply
- All inputs, outputs and clocks are TTL-compatible
- Refresh modes: RAS#-ONLY, CAS#-BEFORE-RAS# (CBR) and HIDDEN; optional self refresh (S)
- 1,024-cycle refresh distributed across 16ms (4MB and 8MB) or 2,048-cycle refresh distributed across 32ms (16MB) or self refresh distributed across 128ms
- FAST PAGE MODE (FPM) or Extended Data-Out (EDO) PAGE MODE access cycles

OPTIONS	MARKING
• Package	
72-pin Small-Outline DIMM (gold)	G
• Timing	
50ns access	-5*
60ns access	-6
• Access Cycles	
FAST PAGE MODE	None
EDO PAGE MODE	X
• Refresh Rates	
Standard Refresh	None
Self Refresh (128ms period)	S

*EDO version only

KEY TIMING PARAMETERS

EDO Operating Mode (4MB and 8MB DIMMs)

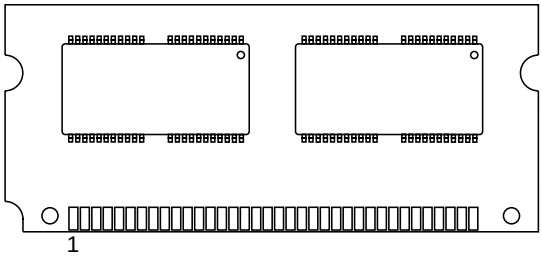
SPEED	tRC	tRAC	tPC	tAA	tCAC	tCAS
-5	84ns	50ns	20ns	25ns	15ns	8ns
-6	104ns	60ns	25ns	30ns	15ns	10ns

EDO Operating Mode (16MB DIMM)

SPEED	tRC	tRAC	tPC	tAA	tCAC	tCAS
-5	84ns	50ns	20ns	25ns	13ns	8ns
-6	104ns	60ns	25ns	30ns	15ns	10ns

PIN ASSIGNMENT (Front View)

72-Pin Small-Outline DIMM



PIN	FRONT	PIN	BACK	PIN	FRONT	PIN	BACK
1	VSS	2	DQ0	37	DQ16	38	DQ17
3	DQ1	4	DQ2	39	VSS	40	CAS0#
5	DQ3	6	DQ4	41	CAS2#	42	CAS3#
7	DQ5	8	DQ6	43	CAS1#	44	RAS0#
9	DQ7	10	VDD	45	NC/RAS1#**	46	NC (A12)
11	PRD1	12	A0	47	WE#	48	NC (A13)
13	A1	14	A2	49	DQ18	50	DQ19
15	A3	16	A4	51	DQ20	52	DQ21
17	A5	18	A6	53	DQ22	54	DQ23
19	A10	20	NC	55	NC	56	DQ24
21	DQ8	22	DQ9	57	DQ25	58	DQ26
23	DQ10	24	DQ11	59	DQ28	60	DQ27
25	DQ12	26	DQ13	61	VDD	62	DQ29
27	DQ14	28	A7	63	DQ30	64	DQ31
29	NC (A11)	30	VDD	65	NC	66	PRD2
31	A8	32	A9	67	PRD3	68	PRD4
33	NC/RAS3#**	34	RAS2#	69	PRD5	70	PRD6
35	DQ15	36	NC	71	PRD7	72	VSS

**8MB version only

NOTE: Symbols in parentheses are not used on these modules but may be used for other modules in this product family. They are for reference only.

FPM Operating Mode

SPEED	tRC	tRAC	tPC	tAA	tCAC	tRP
-6	110ns	60ns	35ns	30ns	15ns	40ns

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PART NUMBERS

EDO Operating Mode

PART NUMBER	CONFIGURATION	REFRESH
MT2LDT132HG-x X	1 Meg x 32	Standard
MT2LDT132HG-x XS	1 Meg x 32	Self
MT4LDT232HG-x X	2 Meg x 32	Standard
MT4LDT232HG-x XS	2 Meg x 32	Self
MT8LDT432HG-x X	4 Meg x 32	Standard
MT8LDT432HG-x XS	4 Meg x 32	Self

x = speed

FPM Operating Mode

PART NUMBER	CONFIGURATION	REFRESH
MT2LDT132HG-x	1 Meg x 32	Standard
MT2LDT132HG-x S	1 Meg x 32	Self
MT4LDT232HG-x	2 Meg x 32	Standard
MT4LDT232HG-x S	2 Meg x 32	Self
MT8LDT432HG-x	4 Meg x 32	Standard
MT8LDT432HG-x S	4 Meg x 32	Self

x = speed

GENERAL DESCRIPTION

The MT2LDT132H(X)(S), MT4LDT232H(X)(S) and MT8LDT432H(X)(S) are randomly accessed 4MB, 8MB and 16MB memories organized in a small-outline x32 configuration. They are specially processed to operate from 3V to 3.6V for low-voltage memory systems.

During READ or WRITE cycles, each bit is uniquely addressed through the address bits, which are entered 10/11 bits (A0-A9/A10) at a time. RAS# is used to latch the first 10/11 bits and CAS# the latter 10/11 bits.

READ and WRITE cycles are selected with the WE# input. A logic HIGH on WE# dictates read mode, while a logic LOW on WE# dictates write mode. During a WRITE cycle, data-in (D) is latched by the falling edge of WE# or CAS#, whichever occurs last. If WE# goes LOW prior to CAS# going LOW, the output pin(s) remain open (High-Z) until the next CAS# cycle.

FAST PAGE MODE

FAST-PAGE-MODE operations allow faster data operations (READ or WRITE) within a row-address-defined page boundary. The FAST-PAGE-MODE cycle is always initiated with a row address strobed in by RAS#, followed by a column address strobed in by CAS#. Additional columns may be accessed by providing valid column addresses, strobing CAS# and holding RAS# LOW, thus executing faster memory cycles. Returning RAS# HIGH terminates the FAST-PAGE-MODE operation.

EDO PAGE MODE

EDO PAGE MODE, designated by the "X" version, is an accelerated FAST-PAGE-MODE cycle. The primary advantage of EDO is the availability of data-out even after CAS# goes back HIGH. EDO provides for CAS# precharge time (^{t}CP) to occur without the output data going invalid. This elimination of CAS# output control provides for pipelined READs.

FAST-PAGE-MODE modules have traditionally turned the output buffers off (High-Z) with the rising edge of CAS#. EDO operates as any DRAM READ or FAST-PAGE-MODE READ, except data will be held valid or become valid after CAS# goes HIGH, as long as RAS# and OE# are held LOW. (Refer to the 1 Meg x 16 (MT4LC1M16E5) DRAM data sheet for additional information on EDO functionality.)

REFRESH

Memory cell data is retained in its correct state by maintaining power and executing any RAS# cycle (READ, WRITE) or RAS# refresh cycle (RAS#-ONLY, CBR or HIDDEN) so that all combinations of RAS# addresses are executed at least every ^{t}REF, regardless of sequence. The CBR REFRESH cycle will invoke the internal refresh counter for automatic RAS# addressing.

An optional self refresh mode is also available. The "S" option allows the user the choice of a fully static, low-power data retention mode or a dynamic refresh mode at the extended refresh period of 128ms. The optional self refresh feature is initiated by performing a CBR REFRESH cycle and holding RAS# LOW for the specified ^{t}RASS.

The self refresh mode is terminated by driving RAS# HIGH for a minimum time of ^{t}RPS. This delay allows for the completion of any internal refresh cycles that may be in process at the time of the RAS# LOW-to-HIGH transition. If the DRAM controller uses a distributed refresh sequence, a burst refresh is not required upon exiting self refresh. However, if the DRAM controller utilizes a RAS#-ONLY or burst refresh sequence, all rows must be refreshed within the average internal refresh rate, prior to the resumption of normal operation.

STANDBY

Returning RAS# and CAS# HIGH terminates a memory cycle and decreases chip current to a reduced standby level. Also, the chip is preconditioned for the next cycle during the RAS# HIGH time.

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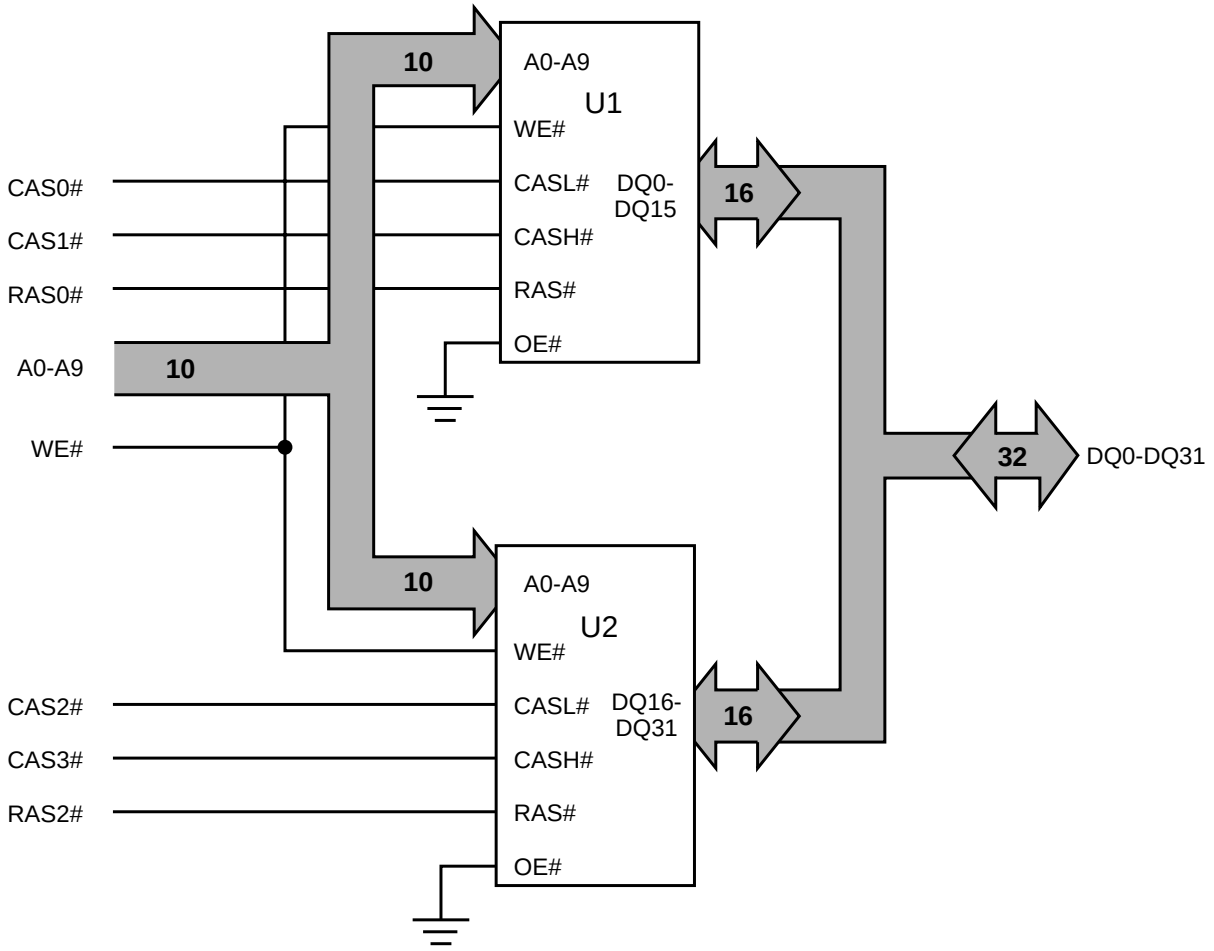
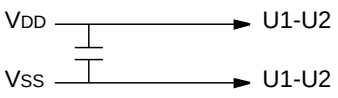
FUNCTIONAL BLOCK DIAGRAM
MT2LDT132H (4MB)





U1-U2 = MT4LC1M16E5(S) EDO PAGE MODE

U1-U2 = MT4LC1M16C3(S) FAST PAGE MODE

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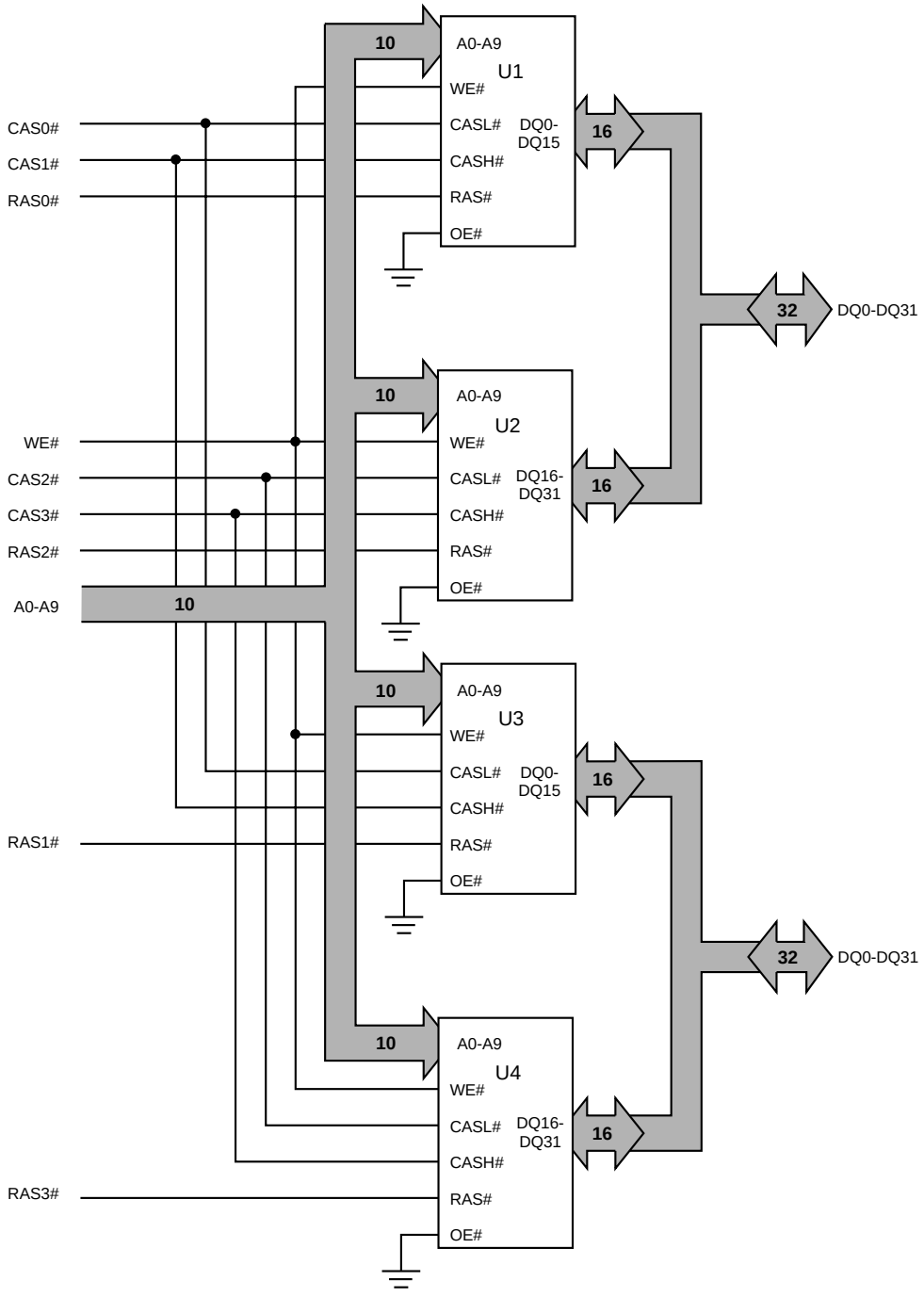
FUNCTIONAL BLOCK DIAGRAM
MT4LDT232H (8MB)



U1-U4 = MT4LC1M16E5(S) EDO PAGE MODE

U1-U4 = MT4LC1M16C3(S) FAST PAGE MODE

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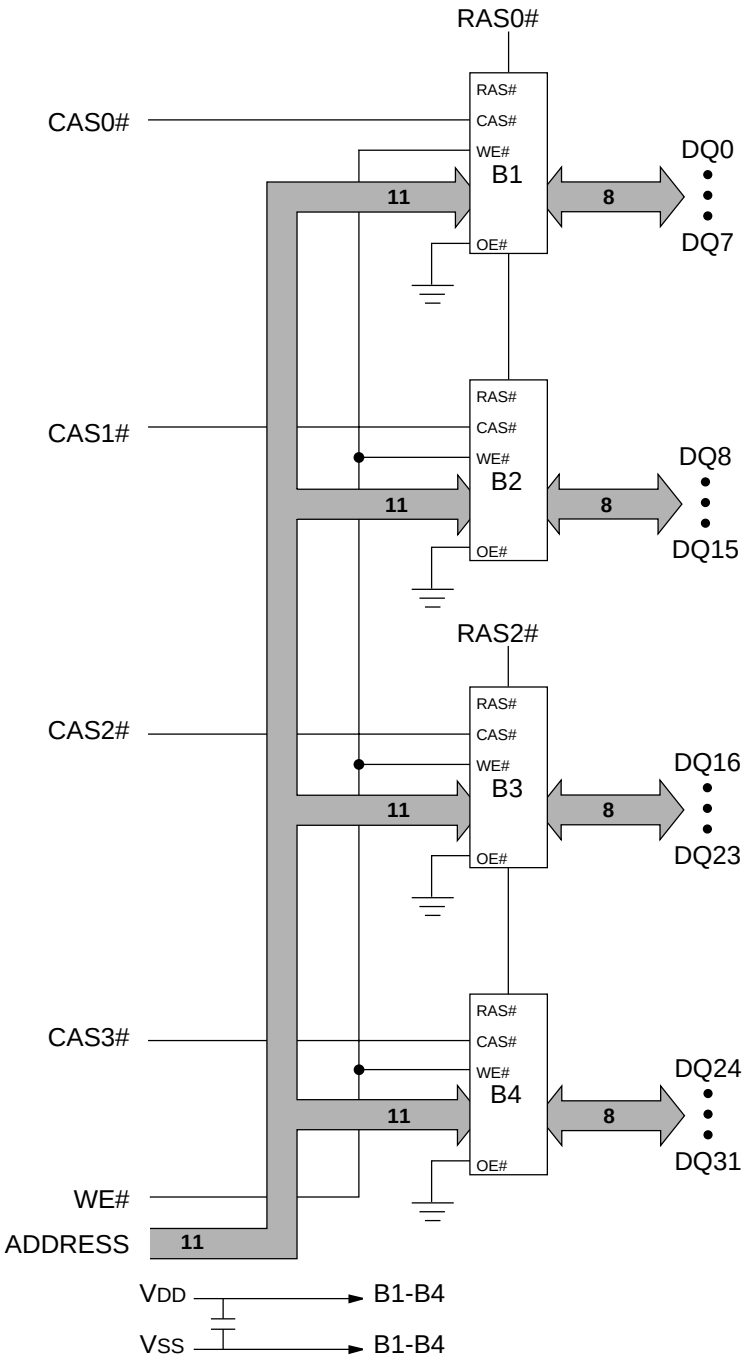
FUNCTIONAL BLOCK DIAGRAM
MT8LDT432H (16MB)



NOTE: B1-B4 are x8 memory blocks consisting of two MT4LC4M4B1(S) DRAMs each for FPM or two MT4LC4M4E8(S) DRAMs each for EDO.

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JEDEC-DEFINED PRESENCE-DETECT – MT2LDT132H (4MB)

SYMBOL	PIN	-5	-6
PRD1	11	NC	NC
PRD2	66	Vss	Vss
PRD3	67	Vss	Vss
PRD4	68	NC	NC
PRD5	69	Vss	NC
PRD6	70	Vss	NC
PRD7	71	X*	X*

JEDEC-DEFINED PRESENCE-DETECT – MT4LDT232H (8MB)

SYMBOL	PIN	-5	-6
PRD1	11	NC	NC
PRD2	66	Vss	Vss
PRD3	67	Vss	Vss
PRD4	68	Vss	Vss
PRD5	69	Vss	NC
PRD6	70	Vss	NC
PRD7	71	X*	X*

JEDEC-DEFINED PRESENCE-DETECT – MT8LDT432H (16MB)

SYMBOL	PIN	-5	-6
PRD1	11	NC	NC
PRD2	66	NC	NC
PRD3	67	Vss	Vss
PRD4	68	NC	NC
PRD5	69	Vss	NC
PRD6	70	Vss	NC
PRD7	71	X*	X*

*NC = Normal Refresh / Vss = Self Refresh

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ABSOLUTE MAXIMUM RATINGS*

Voltage on V_{DD} Supply Relative to V_{SS} ..... -1V to +4.6V
Voltage on Inputs or I/O Pins
Relative to V_{SS} ..... -1V to +4.6V
Operating Temperature, T_A (ambient) ..... 0°C to +70°C
Storage Temperature (plastic)..... -55°C to +125°C
Power Dissipation 4W

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC ELECTRICAL CHARACTERISTICS AND OPERATING CONDITIONS

(Notes: 1) (V_{DD} = +3.3V ±0.3V)

PARAMETER/CONDITION		SYMBOL	SIZE	MIN	MAX	UNITS	NOTES
SUPPLY VOLTAGE		V_{DD}	ALL	3	3.6	V	
INPUT HIGH VOLTAGE: Logic 1; All inputs		V_{IH}	ALL	2	V_{DD} + 0.3	V	27
INPUT LOW VOLTAGE: Logic 0; All inputs		V_{IL}	ALL	-0.5	0.8	V	27
INPUT LEAKAGE CURRENT: Any input 0V ≤ V_{IN} ≤ V_{DD} + 0.3V (All other pins not under test = 0V)	CAS0#-CAS3#	I_{I1}	4MB 8MB 16MB	-2 -4 -4	2 4 4	µA	
	A0-A10, WE#	I_{I2}	4MB 8MB 16MB	-4 -8 -16	4 8 16	µA	
	RAS0#-RAS3#	I_{I3}	4MB 8MB 16MB	-2 -2 -8	2 2 8	µA	
OUTPUT LEAKAGE CURRENT: DQ is disabled; 0V ≤ V_{OUT} ≤ V_{DD} + 0.3V	DQ0-DQ31	I_{OZ}	4MB 8MB 16MB	-10 -20 -10	10 20 10	µA	
OUTPUT LEVELS: Output High Voltage (I_{OUT} = -2mA)		V_{OH}	ALL	2.4	–	V	
Output Low Voltage (I_{OUT} = 2mA)		V_{OL}	ALL	–	0.4	V	

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Icc OPERATING CONDITIONS AND MAXIMUM LIMITS

(Notes: 1, 5, 6) (V_{DD} = +3.3V ±0.3V)

			MAX			
PARAMETER/CONDITION	**SYMBOL**	**SIZE**	**-5***	**-6**	**UNITS**	**NOTES**
STANDBY CURRENT: TTL (RAS# = CAS# = V_{IH})	I_{CC1}	4MB 8MB 16MB	2 4 8	2 4 8	mA	
STANDBY CURRENT: CMOS (RAS# = CAS# = V_{DD} - 0.2V)	I_{CC2}	4MB 8MB 16MB	1 2 4	1 2 4	mA	25
	I_{CC2} (S only)	4MB 8MB 16MB	.3 .6 1.2	.3 .6 1.2	mA	
OPERATING CURRENT: Random READ/WRITE Average power supply current (RAS#, CAS#, address cycling: ^tRC = ^tRC [MIN])	I_{CC3}	4MB 8MB 16MB	360 362 880	340 342 800	mA	3, 22
OPERATING CURRENT: FAST PAGE MODE Average power supply current (RAS# = V_{IL}, CAS#, address cycling: ^tPC = ^tPC [MIN])	I_{CC4}	4MB 8MB 16MB	– – –	340 342 640	mA	3, 22
OPERATING CURRENT: EDO PAGE MODE (“X” version only) Average power supply current (RAS# = V_{IL}, CAS#, address cycling: ^tPC = ^tPC [MIN])	I_{CC5} (X only)	4MB 8MB 16MB	280 282 880	260 262 800	mA	3, 22
REFRESH CURRENT: RAS#-ONLY Average power supply current (RAS# cycling, CAS# = V_{IH}: ^tRC = ^tRC [MIN])	I_{CC6}	4MB 8MB 16MB	360 362 880	340 342 800	mA	3, 22
REFRESH CURRENT: CBR Average power supply current (RAS#, CAS#, address cycling: ^tRC = ^tRC [MIN])	I_{CC7}	4MB 8MB 16MB	360 362 880	340 342 800	mA	3, 4
REFRESH CURRENT: SELF (“S” version only) Average power supply current: CBR cycling with RAS# ≥ ^tRASS (MIN) and CAS# held LOW; WE# = V_{DD} - 0.2V; A0-A10, OE# and D_{IN} = V_{DD} - 0.2V or 0.2V (D_{IN} may be left open)	I_{CC8} (S only)	4MB 8MB 16MB	.6 1.2 2.4	.6 1.2 2.4	mA	3, 4

* EDO version only

CAPACITANCE

		MAX				
PARAMETER	**SYMBOL**	**4MB**	**8MB**	**16MB**	**UNITS**	**NOTES**
Input Capacitance: A0-A10	C_{I1}	14	24	44	pF	2
Input Capacitance: WE#	C_{I2}	18	32	60	pF	2
Input Capacitance: RAS0#-RAS3#	C_{I3}	10	10	32	pF	2
Input Capacitance: CAS0#-CAS3#	C_{I4}	10	18	18	pF	2
Input/Output Capacitance: DQ0-DQ31	C_{IO}	10	18	10	pF	2

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FAST PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - FAST PAGE MODE OPTION		-6			
PARAMETER	**SYMBOL**	**MIN**	**MAX**	**UNITS**	**NOTES**
Access time from column address	^tAA		30	ns	
Column-address hold time (referenced to RAS#)	^tAR	45		ns	
Column-address setup time	^tASC	0		ns	
Row-address setup time	^tASR	0		ns	
Access time from CAS#	^tCAC		15	ns	
Column-address hold time	^tCAH	10		ns	
CAS# pulse width	^tCAS	15	10,000	ns	
CAS# LOW to “Don’t Care” during Self Refresh	^tCHD	15		ns	26
CAS# hold time (CBR Refresh)	^tCHR	10		ns	4
CAS# to output in Low-Z	^tCLZ	3		ns	21
CAS# precharge time	^tCP	10		ns	13
Access time from CAS# precharge	^tCPA		35	ns	
CAS# to RAS# precharge time	^tCRP	5		ns	
CAS# hold time	^tCSH	60		ns	
CAS# setup time (CBR Refresh)	^tCSR	5		ns	4
WRITE command to CAS# lead time	^tCWL	15		ns	
Data-in hold time	^tDH	10		ns	18
Data-in setup time	^tDS	0		ns	18
Output buffer turn-off delay	^tOFF	3	15	ns	17, 21, 23
FAST-PAGE-MODE READ or WRITE cycle time	^tPC	35		ns	
Access time from RAS#	^tRAC		60	ns	
RAS# to column-address delay time	^tRAD	15		ns	15
Row-address hold time	^tRAH	10		ns	

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FAST PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - FAST PAGE MODE OPTION		-6			
PARAMETER	**SYMBOL**	**MIN**	**MAX**	**UNITS**	**NOTES**
RAS# pulse width	^{t}RAS	60	10,000	ns	
RAS# pulse width (FAST PAGE MODE)	^{t}RASP	60	125,000	ns	
RAS# pulse width during Self Refresh	^{t}RASS	100		µs	26
Random READ or WRITE cycle time	^{t}RC	110		ns	
RAS# to CAS# delay time	^{t}RCD	20		ns	14
READ command hold time (referenced to CAS#)	^{t}RCH	0		ns	16
READ command setup time	^{t}RCS	0		ns	
Refresh period (1,024 cycles) (4MB and 8MB)	^{t}REF		16	ms	
Refresh period (2,048 cycles) (16MB)	^{t}REF		32	ms	
Refresh period (1,024 and 2,048 cycles) “S” version	^{t}REF		128	ms	26
RAS# precharge time	^{t}RP	40		ns	
RAS# to CAS# precharge time	^{t}RPC	0		ns	
RAS# precharge time exiting Self Refresh	^{t}RPS	110		ns	26
READ command hold time (referenced to RAS#)	^{t}RRH	0		ns	16
RAS# hold time	^{t}RSH	15		ns	
WRITE command to RAS# lead time	^{t}RWL	15		ns	
Transition time (rise or fall)	^{t}T	2	50	ns	
WRITE command hold time	^{t}WCH	10		ns	
WRITE command hold time (referenced to RAS#)	^{t}WCR	45		ns	
WE# command setup time	^{t}WCS	0		ns	
WRITE command pulse width	^{t}WP	10		ns	
WE# hold time (CBR Refresh)	^{t}WRH	10		ns	
WE# setup time (CBR Refresh)	^{t}WRP	10		ns	

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EDO PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - EDO PAGE MODE OPTION		-5		-6			
PARAMETER	**SYMBOL**	**MIN**	**MAX**	**MIN**	**MAX**	**UNITS**	**NOTES**
Access time from column address	^tAA		25		30	ns	
Column-address setup to CAS# precharge	^tACH	12		15		ns	
Column-address hold time (referenced to RAS#)	^tAR	38		45		ns	
Column-address setup time	^tASC	0		0		ns	
Row-address setup time	^tASR	0		0		ns	
Access time from CAS#	^tCAC		13/15*		15	ns	
Column-address hold time	^tCAH	8		10		ns	
CAS# pulse width	^tCAS	8	10,000	10	10,000	ns	
CAS# LOW to “Don’t Care” during Self Refresh	^tCHD	15		15		ns	26
CAS# hold time (CBR Refresh)	^tCHR	8		10		ns	4
CAS# to output in Low-Z	^tCLZ	0		0		ns	
Data output hold after next CAS# LOW	^tCOH	3		3		ns	
CAS# precharge time	^tCP	8		10		ns	13
Access time from CAS# precharge	^tCPA		28		35	ns	
CAS# to RAS# precharge time	^tCRP	5		5		ns	
CAS# hold time	^tCSH	38		45		ns	
CAS# setup time (CBR Refresh)	^tCSR	5		5		ns	4
WRITE command to CAS# lead time	^tCWL	8		10		ns	
Data-in hold time	^tDH	8		10		ns	18
Data-in setup time	^tDS	0		0		ns	18
Output buffer turn-off delay	^tOFF	0	12	0	15	ns	17, 23
EDO-PAGE-MODE READ or WRITE cycle time	^tPC	20		25		ns	
Access time from RAS#	^tRAC		50		60	ns	
RAS# to column-address delay time	^tRAD	9		12		ns	15
Row-address hold time	^tRAH	9		10		ns	
RAS# pulse width	^tRAS	50	10,000	60	10,000	ns	
RAS# pulse width (EDO PAGE MODE)	^tRASP	50	125,000	60	125,000	ns	
RAS# pulse width during Self Refresh	^tRASS	100		100		µs	26
Random READ or WRITE cycle time	^tRC	84		104		ns	
RAS# to CAS# delay time	^tRCD	11		14		ns	14

*4MB and 8MB DIMMs

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EDO PAGE MODE
AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 12, 19) (V_{DD} = +3.3V ±0.3V)

AC CHARACTERISTICS - EDO PAGE MODE OPTION		-5		-6			
PARAMETER	**SYMBOL**	**MIN**	**MAX**	**MIN**	**MAX**	**UNITS**	**NOTES**
READ command hold time (referenced to CAS#)	^{t}RCH	0		0		ns	16
READ command setup time	^{t}RCS	0		0		ns	
Refresh period (1,024 cycles) (4MB and 8MB)	^{t}REF		16		16	ms	
Refresh period (2,048 cycles) (16MB)	^{t}REF		32		32	ms	
Refresh period (1,024 and 2,048 cycles) “S” version	^{t}REF		128		128	ms	26
RAS# precharge time	^{t}RP	30		40		ns	
RAS# to CAS# precharge time	^{t}RPC	5		5		ns	
RAS# precharge time exiting Self Refresh	^{t}RPS	90		105		ns	26
READ command hold time (referenced to RAS#)	^{t}RRH	0		0		ns	16
RAS# hold time	^{t}RSH	13		15		ns	
WRITE command to RAS# lead time	^{t}RWL	13		15		ns	
Transition time (rise or fall)	^{t}T	2	50	2	50	ns	
WRITE command hold time	^{t}WCH	8		10		ns	
WRITE command hold time (referenced to RAS#)	^{t}WCR	38		45		ns	
WE# command setup time	^{t}WCS	0		0		ns	
Output disable delay from WE#	^{t}WHZ	0	12	0	15	ns	
WRITE command pulse width	^{t}WP	5		5		ns	
WE# pulse to disable at CAS# HIGH	^{t}WPZ	10		10		ns	
WE# hold time (CBR Refresh)	^{t}WRH	8		10		ns	
WE# setup time (CBR Refresh)	^{t}WRP	8		10		ns	

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NOTES

1. All voltages referenced to V_{SS}.
2. This parameter is sampled. V_{DD} = +3.3V; f = 1 MHz.
3. I_{CC} is dependent on output loading and cycle rates. Specified values are obtained with minimum cycle time and the outputs open.
4. Enables on-chip refresh and address counters.
5. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range is ensured.
6. An initial pause of 100µs is required after power-up, followed by eight RAS# REFRESH cycles (RAS#-ONLY or CBR with WE# HIGH), before proper device operation is ensured. The eight RAS# cycle wake-ups should be repeated any time the ^{t}REF refresh requirement is exceeded.
7. AC characteristics assume ^{t}T = 5ns for FPM and ^{t}T = 2.5ns for EDO.
8. V_{IH} (MIN) and V_{IL} (MAX) are reference levels for measuring timing of input signals. Transition times are measured between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}).
9. In addition to meeting the transition rate specification, all input signals must transit between V_{IH} and V_{IL} (or between V_{IL} and V_{IH}) in a monotonic manner.
10. If CAS# = V_{IH}, data output is High-Z.
11. If CAS# = V_{IL}, data output may contain data from the last valid READ cycle.
12. Measured with a load equivalent to two TTL gates and 100pF, V_{OL} = 0.8V and V_{OH} = 2V.
13. If CAS# is LOW at the falling edge of RAS#, Q will be maintained from the previous cycle. To initiate a new cycle and clear the data-out buffer, CAS# must be pulsed HIGH for ^{t}CP.
14. The ^{t}RCD (MAX) limit is no longer specified. ^{t}RCD (MAX) was specified as a reference point only. If ^{t}RCD was greater than the specified ^{t}RCD (MAX) limit, then access time was controlled exclusively by ^{t}CAC (^{t}RAC [MIN] no longer applied). With or without the ^{t}RCD (MAX) limit, ^{t}AA and ^{t}CAC must always be met.
15. The ^{t}RAD (MAX) limit is no longer specified. ^{t}RAD (MAX) was specified as a reference point only. If ^{t}RAD was greater than the specified ^{t}RAD (MAX) limit, then access time was controlled exclusively by ^{t}AA (^{t}RAC and ^{t}CAC no longer applied). With or without the ^{t}RAD (MAX) limit, ^{t}AA, ^{t}RAC and ^{t}CAC must always be met.
16. Either ^{t}RCH or ^{t}RRH must be satisfied for a READ cycle.
17. ^{t}OFF (MAX) defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL}.
18. These parameters are referenced to CAS# leading edge in EARLY WRITE cycles.
19. OE# is tied permanently LOW; LATE WRITE or READ-MODIFY-WRITE operations are not permissible and should not be attempted.
20. A HIDDEN REFRESH may also be performed after a WRITE cycle. In this case, WE# = LOW and OE# = HIGH.
21. The 3ns minimum is a parameter guaranteed by design.
22. Column address changed once each cycle.
23. With the FPM option, ^{t}OFF is determined by the first RAS# or CAS# signal to transition HIGH. In comparison, ^{t}OFF on an EDO option is determined by the latter of the RAS# and CAS# signals to transition HIGH.
24. Applies to both FPM and EDO operating modes.
25. All other inputs at 0.2V or V_{DD} - 0.2V.
26. “S” version only.
27. V_{IH} overshoot: V_{IH} (MAX) = V_{DD} + 2V for a pulse width ≤ 10ns, and the pulse width cannot be greater than one third of the cycle rate. V_{IL} undershoot: V_{IL} (MIN) = -2V for a pulse width ≤ 10ns, and the pulse width cannot be greater than one third of the cycle rate.

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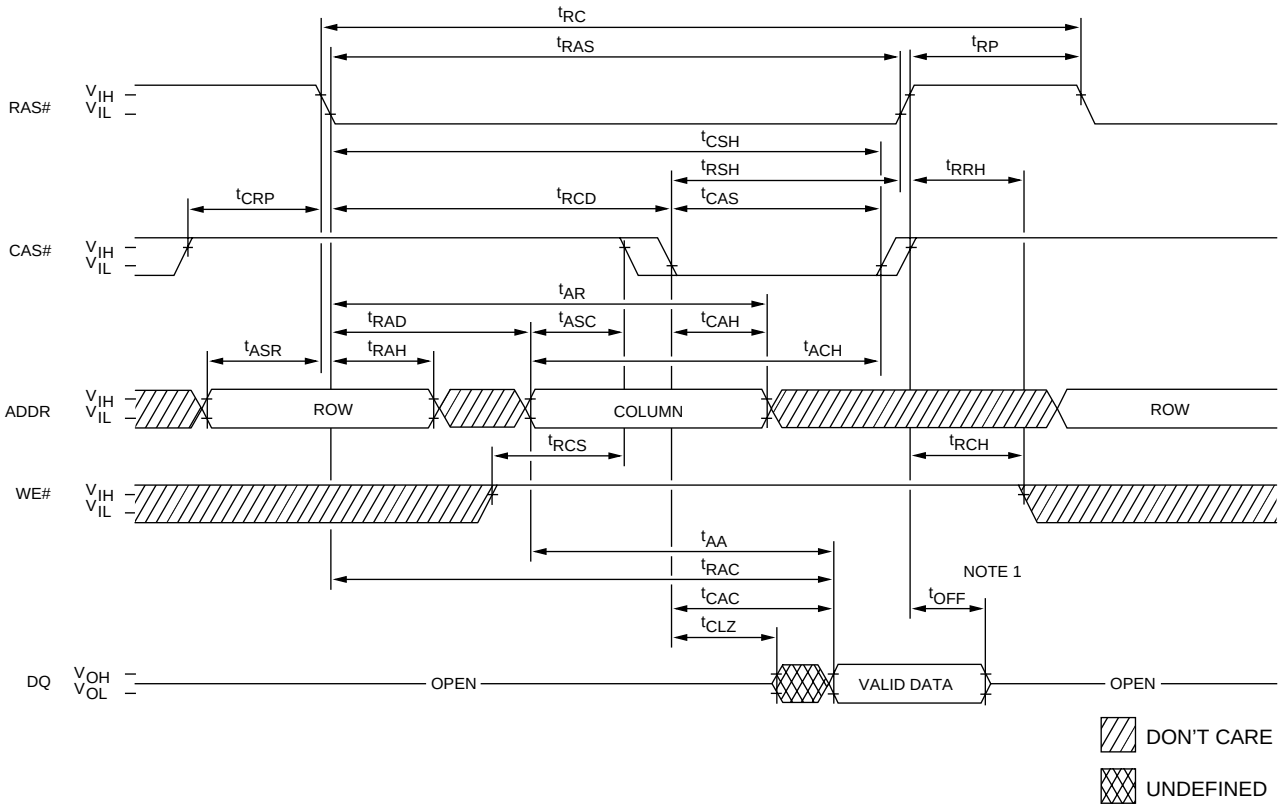
READ CYCLE [24]



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tAA		25		30	ns
tACH (EDO)	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13/15**		15	ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	–	–	15	10,000	ns
tCLZ (EDO)	0		0		ns
tCLZ (FPM)	–		3		ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	–		60		ns
tOFF (EDO)	0	12	0	15	ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tOFF (FPM)	–	–	3	15	ns
tRAC		50		60	ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	–		15		ns
tRAH	9		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (EDO)	84		104		ns
tRC (FPM)	–		110		ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	–		20		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRRH	0		0		ns
tRSH	13		15		ns

*EDO version only
**4MB and 8MB DIMMs

NOTE: 1. For EDO, tOFF is referenced from rising edge of RAS# or CAS#, whichever occurs last. For FPM, tOFF is referenced from rising edge of RAS# or CAS#, whichever occurs first.

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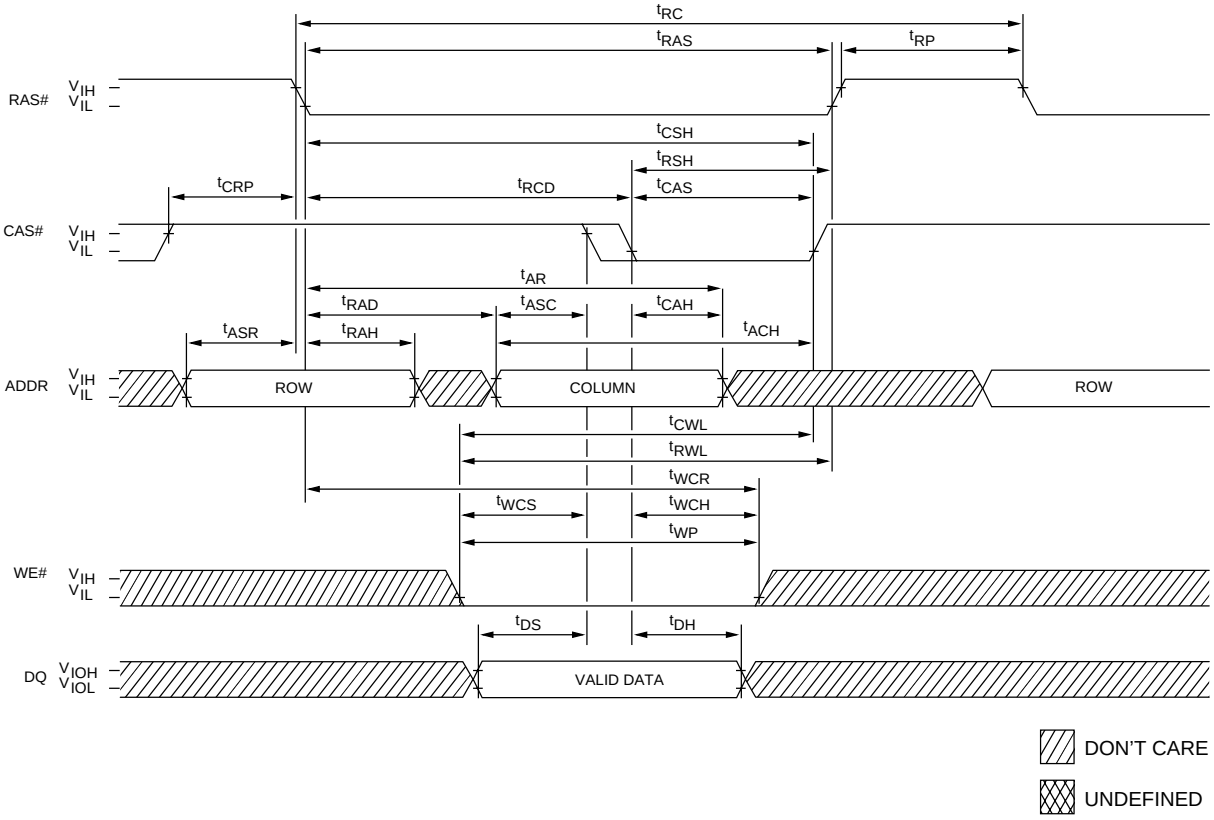
EARLY WRITE CYCLE [24]



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tACH (EDO)	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAH	8		10		ns
tCAS (FPM)	–	–	15	10,000	ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCRP	5		5		ns
tCSH (FPM)	–		60		ns
tCSH (EDO)	38		45		ns
tCWL (FPM)	–		15		ns
tCWL (EDO)	8		10		ns
tDH	8		10		ns
tDS	0		0		ns
tRAD (FPM)	–		15		ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tRAD (EDO)	9		12		ns
tRAH	9		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (FPM)	–		110		ns
tRC (EDO)	84		104		ns
tRCD (FPM)	–		20		ns
tRCD (EDO)	11		14		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWL	13		15		ns
tWCH	8		10		ns
tWCR	38		45		ns
tWCS	0		0		ns
tWP (FPM)	–		10		ns
tWP (EDO)	5		5		ns

*EDO version only

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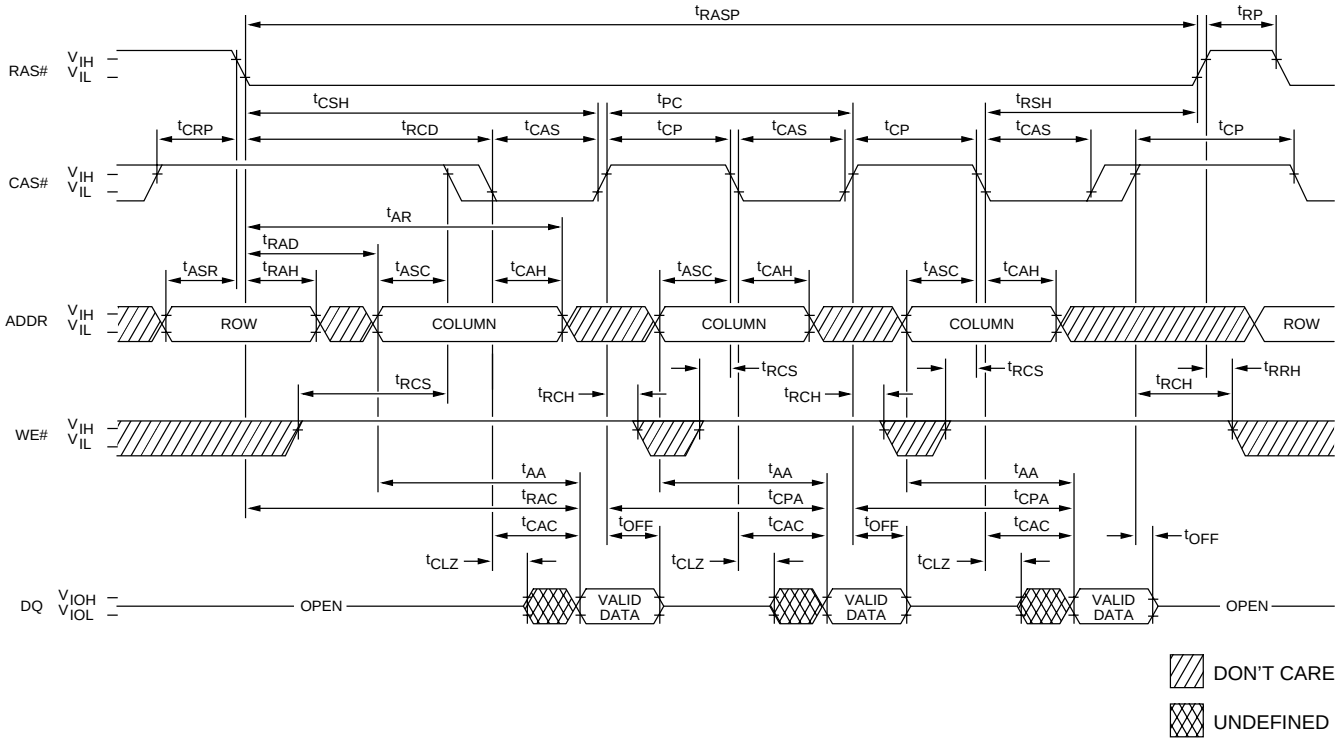
FAST-PAGE-MODE READ CYCLE



FAST PAGE MODE TIMING PARAMETERS

SYMBOL	-6 MIN	-6 MAX	UNITS
tAA		30	ns
tAR	45		ns
tASC	0		ns
tASR	0		ns
tCAC		15	ns
tCAH	10		ns
tCAS	15	10,000	ns
tCLZ	3		ns
tCP	10		ns
tCPA		35	ns
tCRP	5		ns
tCSH	60		ns

SYMBOL	-6 MIN	-6 MAX	UNITS
tOFF	3	15	ns
tPC	35		ns
tRAC		60	ns
tRAD	15		ns
tRAH	10		ns
tRASP	60	125,000	ns
tRCD	20		ns
tRCH	0		ns
tRCS	0		ns
tRP	40		ns
tRRH	0		ns
tRSH	15		ns

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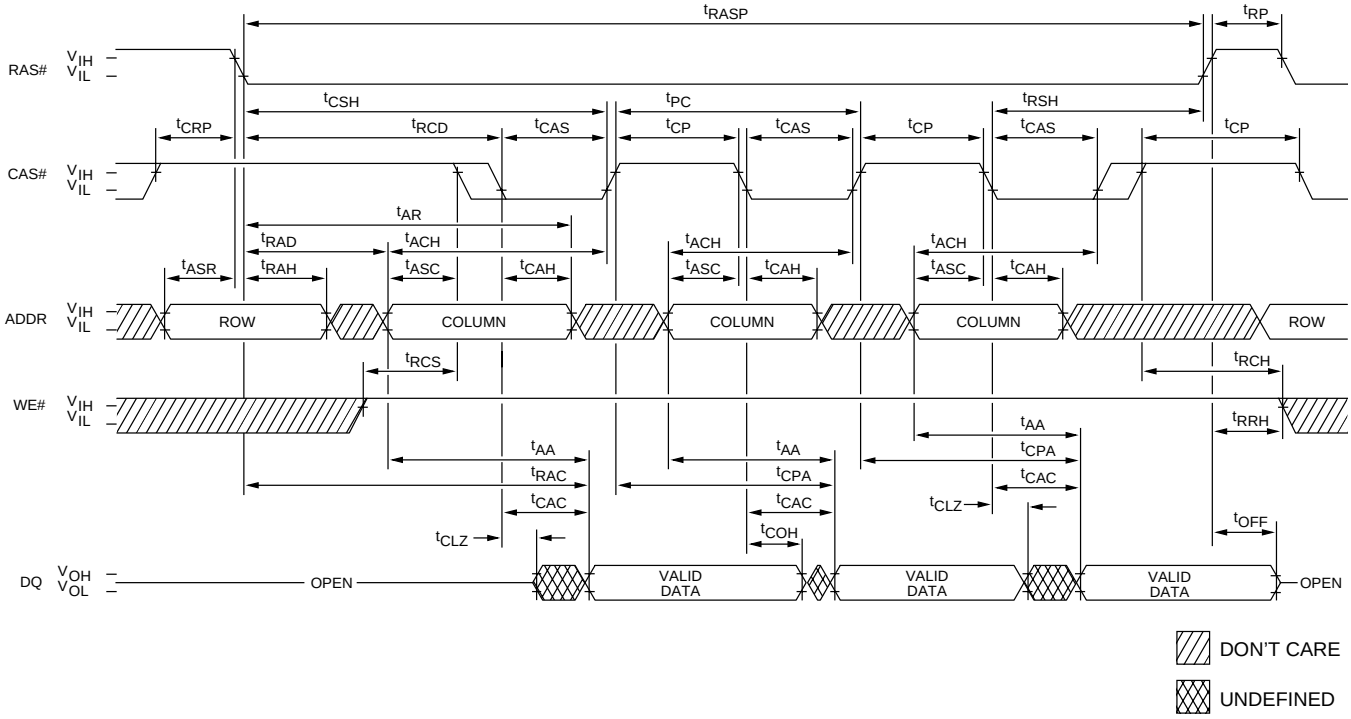
EDO-PAGE-MODE READ CYCLE



EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13/15*		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCLZ	0		0		ns
tCOH	3		3		ns
tCP	8		10		ns
tCPA		28		35	ns
tCRP	5		5		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tCSH	38		45		ns
tOFF	0	12	0	15	ns
tPC	20		25		ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRRH	0		0		ns
tRSH	13		15		ns

*4MB and 8MB DIMMs

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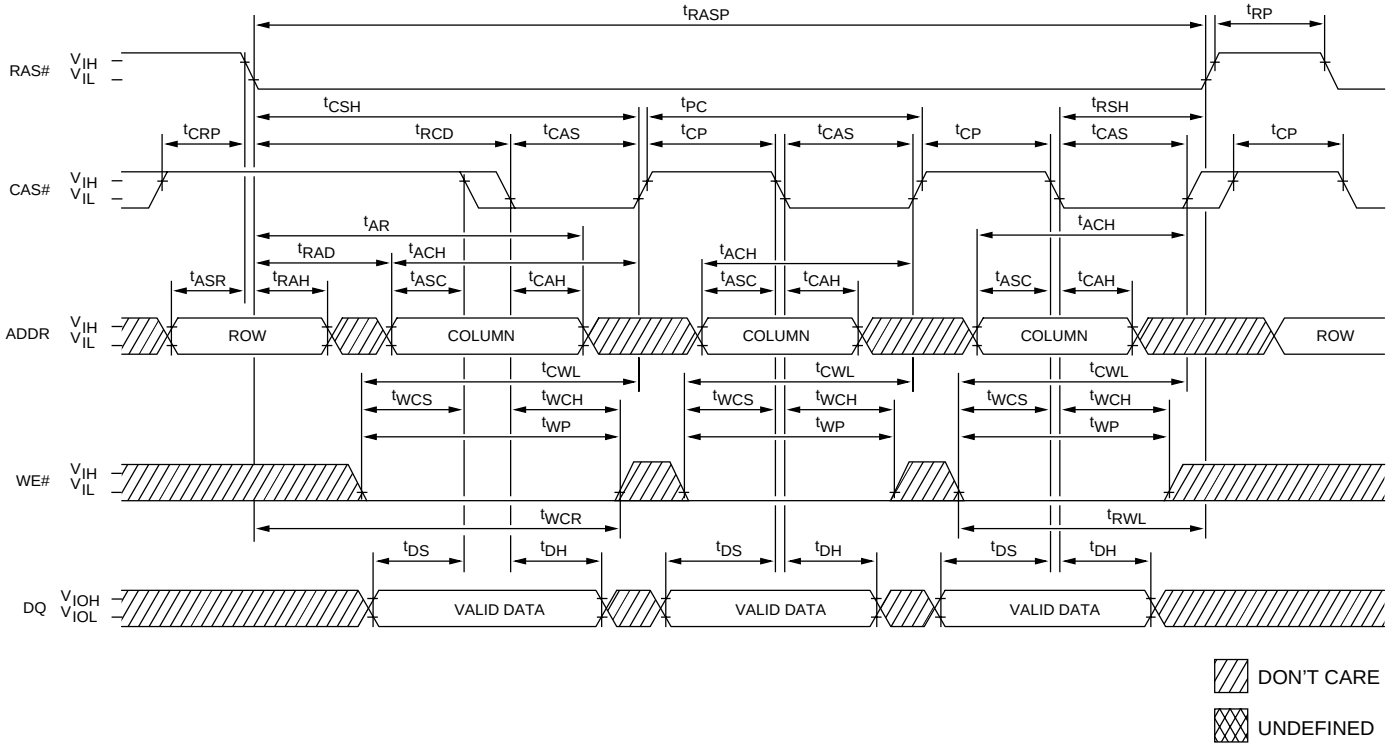
FAST/EDO-PAGE-MODE EARLY WRITE CYCLE [24]



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tACH (EDO)	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAH	8		10		ns
tCAS (EDO)	8	10,000	10	10,000	ns
tCAS (FPM)	–	–	15	10,000	ns
tCP	8		10		ns
tCRP	5		5		ns
tCSH (EDO)	38		45		ns
tCSH (FPM)	–		60		ns
tCWL (EDO)	8		10		ns
tCWL (FPM)	–		15		ns
tDH	8		10		ns
tDS	0		0		ns
tPC (EDO)	20		25		ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tPC (FPM)	–		35		ns
tRAD (EDO)	9		12		ns
tRAD (FPM)	–		15		ns
tRAH	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD (EDO)	11		14		ns
tRCD (FPM)	–		20		ns
tRP	30		40		ns
tRSH	13		15		ns
tRWL	13		15		ns
tWCH	8		10		ns
tWCR	38		45		ns
tWCS	0		0		ns
tWP (EDO)	5		5		ns
tWP (FPM)	–		10		ns

*EDO version only

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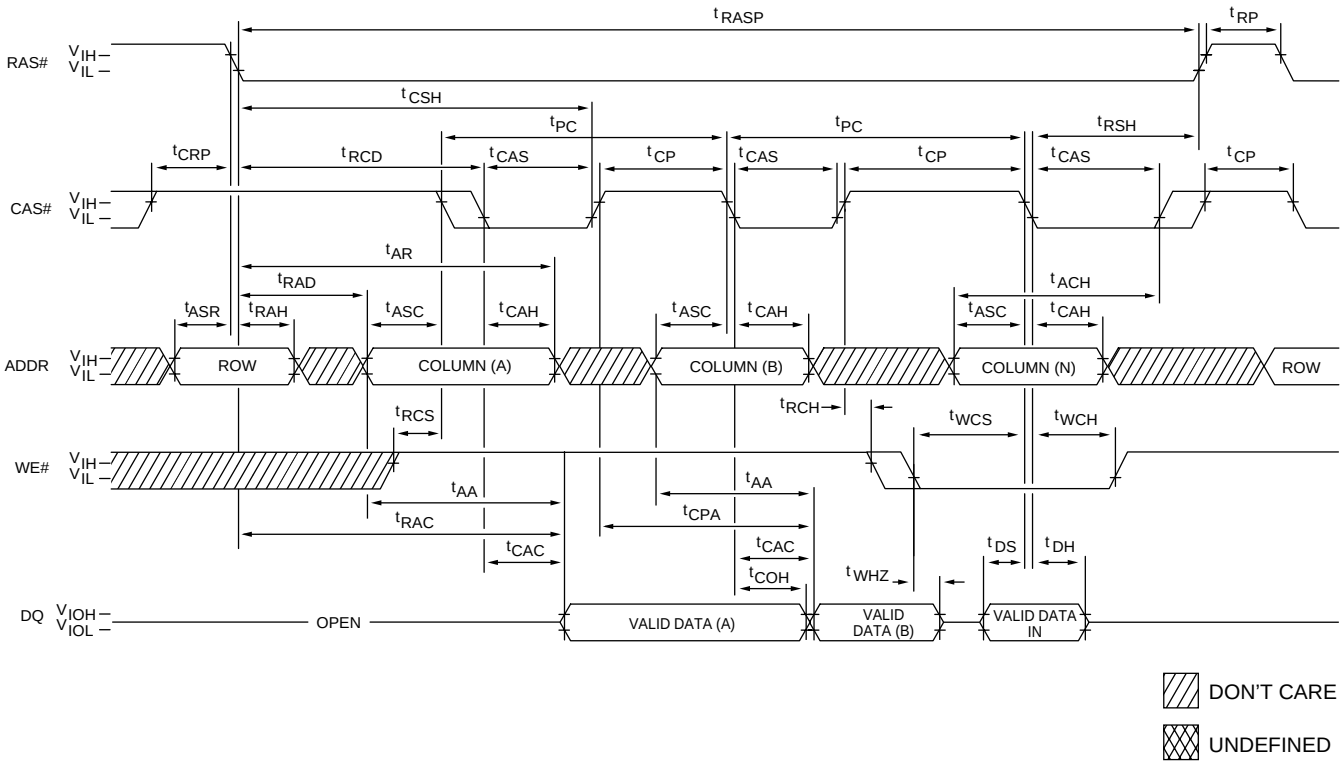
EDO-PAGE-MODE READ EARLY WRITE CYCLE
(Pseudo READ-MODIFY-WRITE)



EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tACH	12		15		ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13/15*		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCOH	3		3		ns
tCP	8		10		ns
tCPA		28		35	ns
tCRP	5		5		ns
tCSH	38		45		ns
tDH	8		10		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tDS	0		0		ns
tPC	20		25		ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRASP	50	125,000	60	125,000	ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tRP	30		40		ns
tRSH	13		15		ns
tWCH	8		10		ns
tWCS	0		0		ns
tWHZ	0	12	0	15	ns

*4MB and 8MB DIMMs

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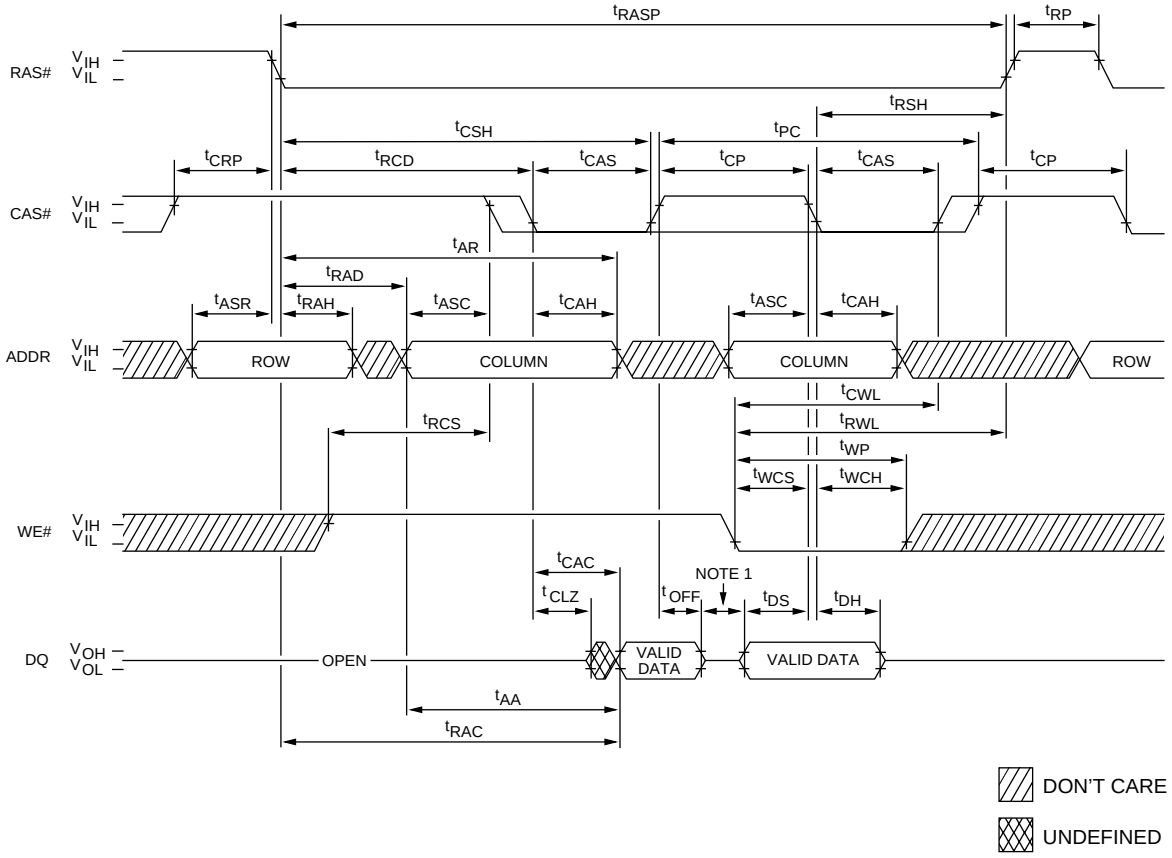
FAST-PAGE-MODE READ EARLY WRITE CYCLE
(Pseudo READ-MODIFY-WRITE)



FAST PAGE MODE TIMING PARAMETERS

SYMBOL	-6 MIN	-6 MAX	UNITS
tAA		30	ns
tAR	45		ns
tASC	0		ns
tASR	0		ns
tCAC		15	ns
tCAH	10		ns
tCAS	15	10,000	ns
tCLZ	3		ns
tCP	10		ns
tCRP	5		ns
tCSH	60		ns
tCWL	15		ns
tDH	10		ns
tDS	0		ns

SYMBOL	-6 MIN	-6 MAX	UNITS
tOFF	3	15	ns
tPC	35		ns
tRAC		60	ns
tRAD	15		ns
tRAH	10		ns
tRASP	60	125,000	ns
tRCD	20		ns
tRCS	0		ns
tRP	40		ns
tRSH	15		ns
tRWL	15		ns
tWCH	10		ns
tWCS	0		ns
tWP	10		ns

NOTE: 1. Do not drive data prior to tristate.

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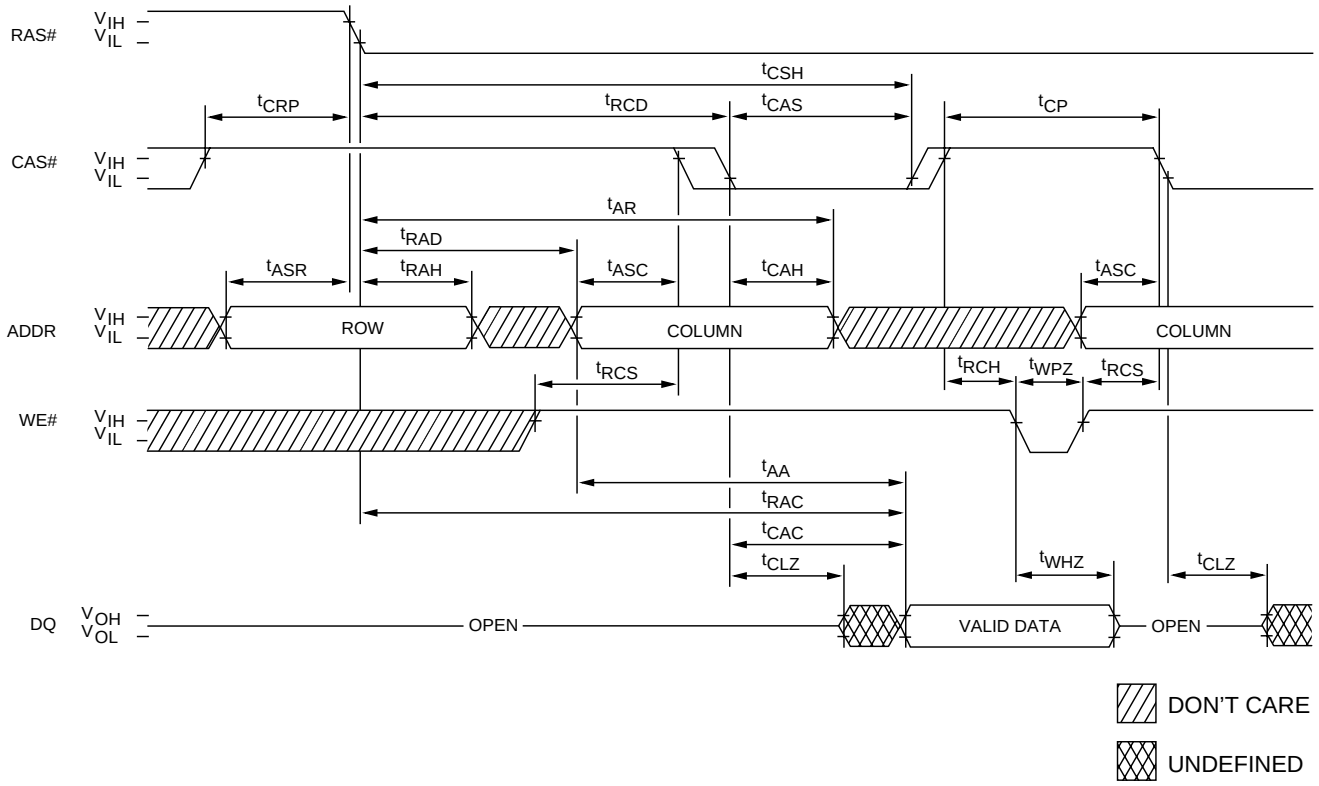
EDO READ CYCLE
(with WE#-controlled disable)



EDO PAGE MODE TIMING PARAMETERS

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tAA		25		30	ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13/15*		15	ns
tCAH	8		10		ns
tCAS	8	10,000	10	10,000	ns
tCLZ	0		0		ns
tCP	8		10		ns
tCRP	5		5		ns

SYMBOL	-5 MIN	-5 MAX	-6 MIN	-6 MAX	UNITS
tCSH	38		45		ns
tRAC		50		60	ns
tRAD	9		12		ns
tRAH	9		10		ns
tRCD	11		14		ns
tRCH	0		0		ns
tRCS	0		0		ns
tWHZ	0	12	0	15	ns
tWPZ	10		10		ns

*4MB and 8MB DIMMs

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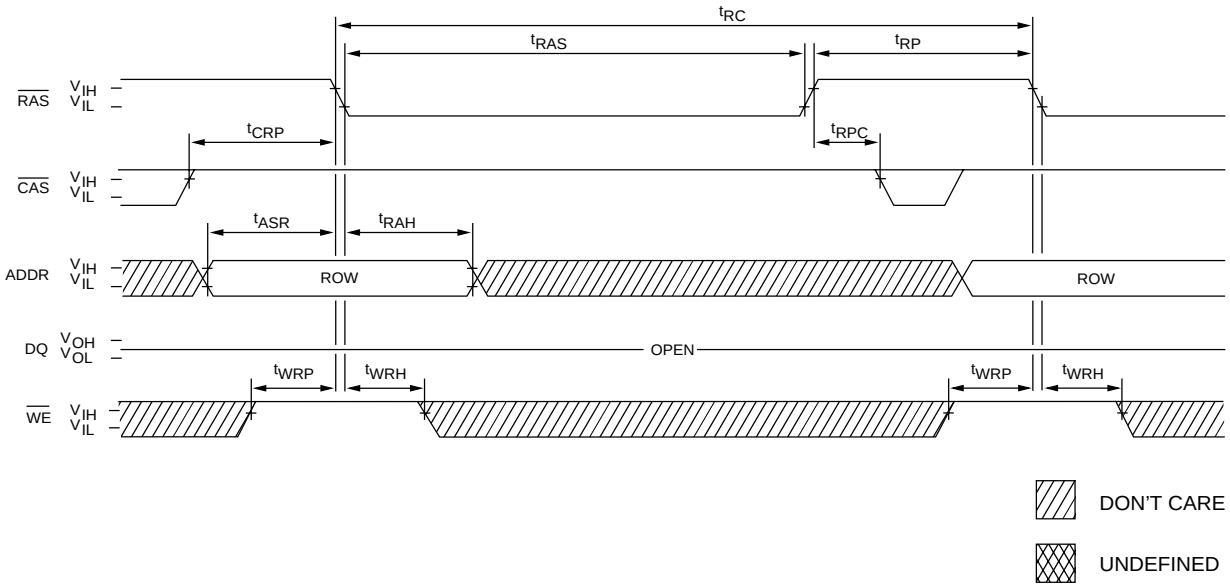
RAS#-ONLY REFRESH CYCLE [24]



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tASR	0		0		ns
tCRP	5		5		ns
tCSR	5		5		ns
tRAH	9		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (FPM)	–		110		ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tRC (EDO)	84		104		ns
tRP	30		40		ns
tRPC (FPM)	–		0		ns
tRPC (EDO)	5		5		ns
tWRH	8		10		ns
tWRP	8		10		ns

*EDO version only

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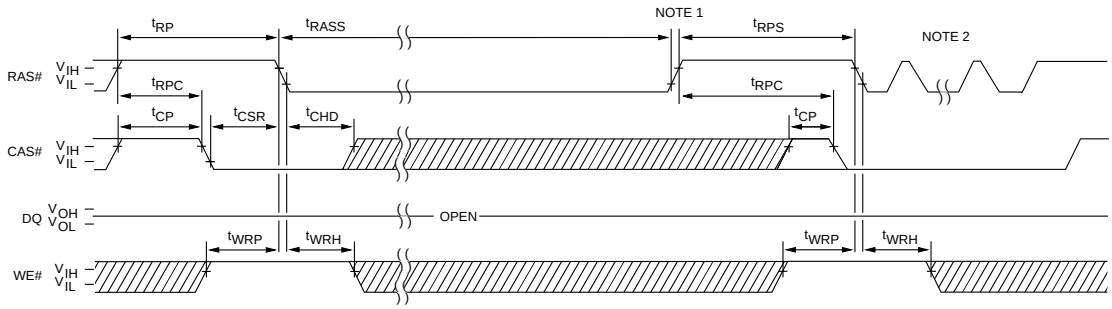
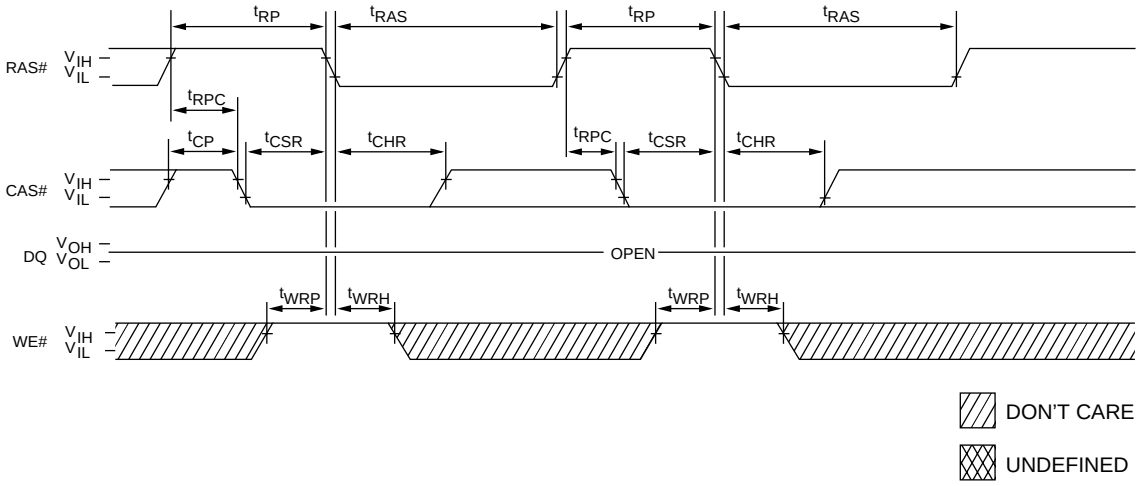
SELF REFRESH CYCLE [24, 26]

(Addresses = DON'T CARE)



CBR REFRESH CYCLE [24]

(Addresses = DON'T CARE)



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tCHD	15		15		ns
tCHR	8		10		ns
tCP	8		10		ns
tCSR	5		5		ns
tRAS	50	10,000	60	10,000	ns
tRASS	100		100		µs
tRP	30		40		ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tRPC (FPM)	–		0		ns
tRPC (EDO)	5		5		ns
tRPS (FPM)	–		110		ns
tRPS (EDO)	90		105		ns
tWRH	8		10		ns
tWRP	8		10		ns

*EDO version only

NOTE: 1. Once tRASS (MIN) is met and RAS# remains LOW, the DRAM will enter Self Refresh mode.
2. Once tRPS is satisfied, a complete burst of all rows should be executed.

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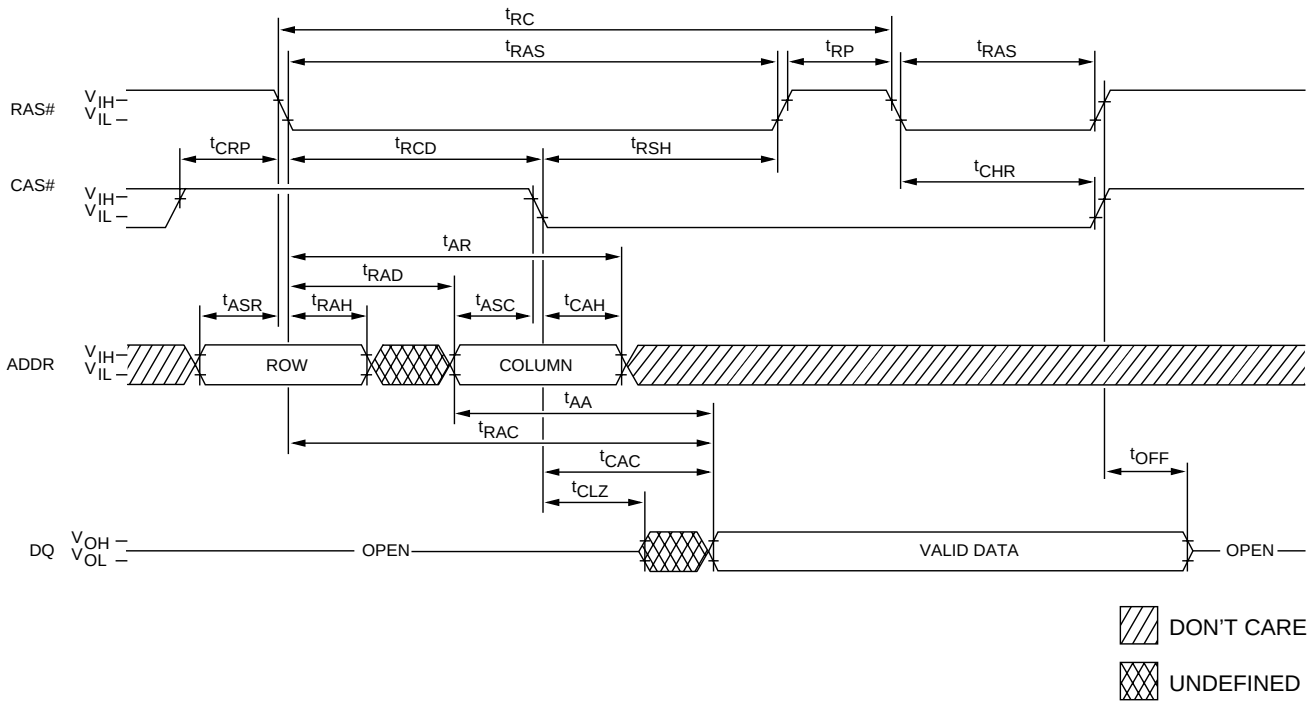
HIDDEN REFRESH CYCLE [20, 24]
(WE# = HIGH)



FAST PAGE MODE AND EDO PAGE MODE TIMING PARAMETERS

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tAA		25		30	ns
tAR	38		45		ns
tASC	0		0		ns
tASR	0		0		ns
tCAC		13/15**		15	ns
tCAH	8		10		ns
tCHR	8		10		ns
tCLZ (FPM)	–		3		ns
tCLZ (EDO)	0		0		ns
tCRP	5		5		ns
tOFF (FPM)	–	–	3	15	ns
tOFF (EDO)	0	12	0	15	ns

	-5*		-6		
SYMBOL	MIN	MAX	MIN	MAX	UNITS
tRAC		50		60	ns
tRAD (FPM)	–		15		ns
tRAD (EDO)	9		12		ns
tRAH	9		10		ns
tRAS	50	10,000	60	10,000	ns
tRC (FPM)	–		110		ns
tRC (EDO)	84		104		ns
tRCD (FPM)	–		20		ns
tRCD (EDO)	11		14		ns
tRP	30		40		ns
tRSH	13		15		ns

*EDO version only
**4MB and 8MB DIMMs

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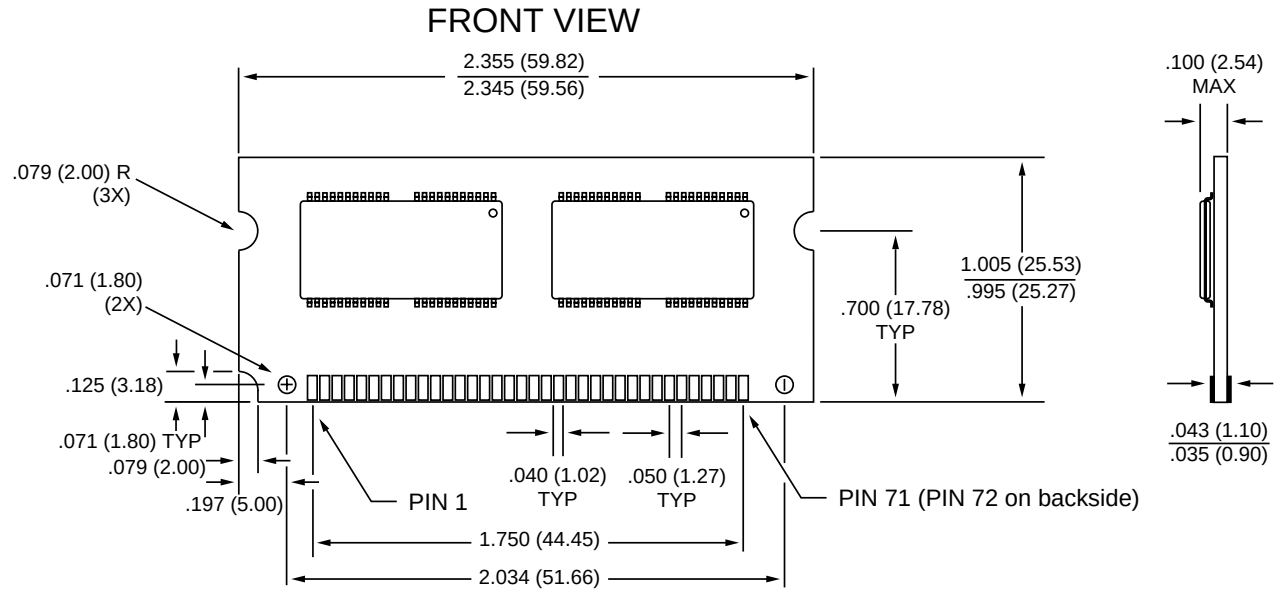
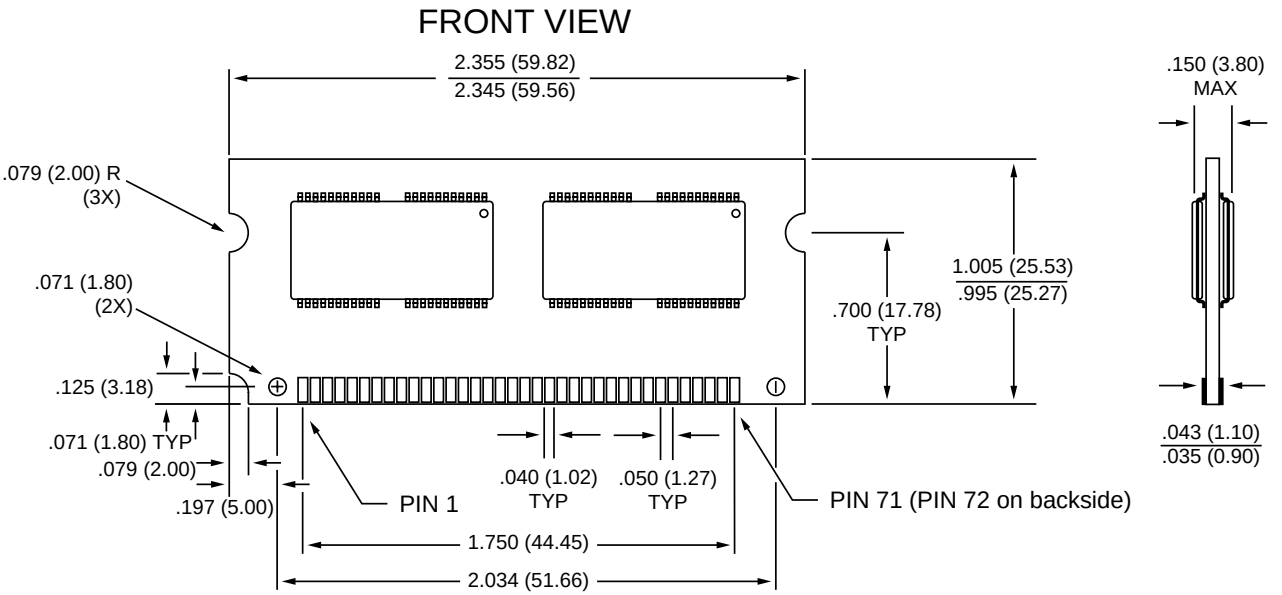
72-PIN SODIMM

DG-1 (1 Meg x 32)



72-PIN SODIMM

DG-2 (2 Meg x 32)



NOTE: 1. All dimensions in inches (millimeters) $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.

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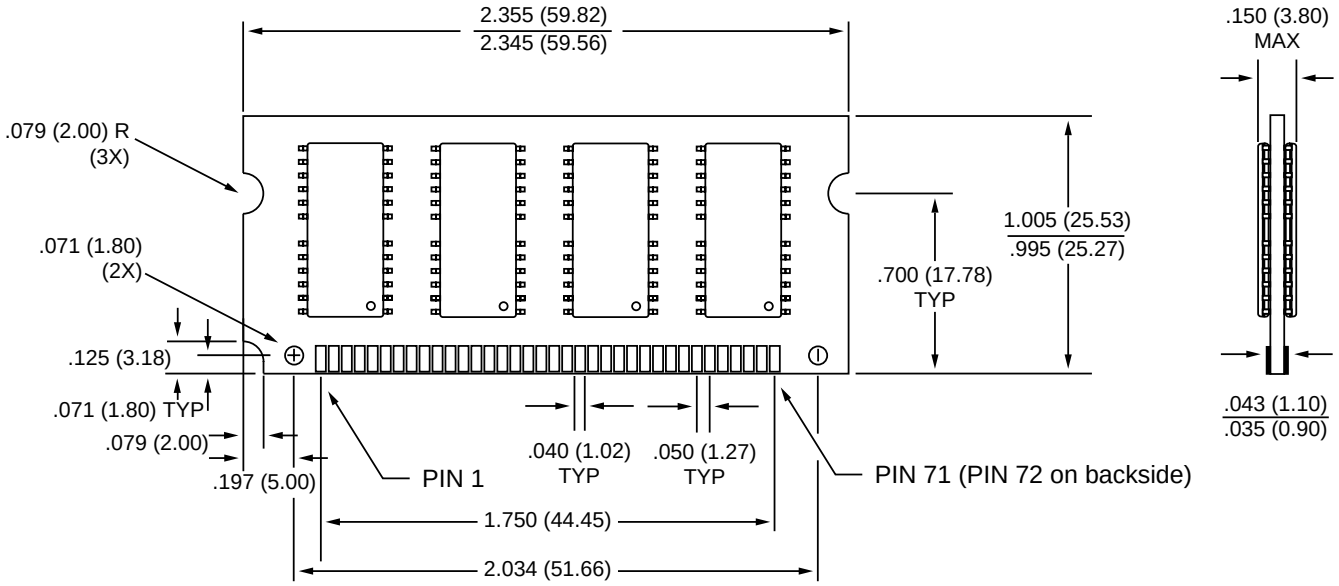
72-PIN SODIMM

DG-3 (4 Meg x 32)

FRONT VIEW



NOTE: 1. All dimensions in inches (millimeters) $\frac{\text{MAX}}{\text{MIN}}$ or typical where noted.

MICRON® TECHNOLOGY, INC.

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